LISTING OF THE CLAIMS:

1. (Currently Amended) An electronic device, comprising:

a semiconductor chip having a first surface in electrical communication with a substrate;

a heat spreader being arrayed in closely spaced relationship with an opposite surface of said semiconductor chip; and

adhesive means bonding said heat spreader to said semiconductor chip, said adhesive means comprising an electrically conductive silicone adhesive positioned in an essentially single spot on a center or an areal surface portion of said semiconductor chip, and an electrically non-conductive silicone adhesive of an extensively larger surface area than said single spot formed by said electrically conductive silicone adhesive extending about said electrically conductive silicone adhesive for concurrently bonding said heat spreader to said semiconductor chip.

2. (Original) An electronic device, as claimed in Claim 1, wherein said heat spreader comprises an electrically conductive material forming an electrical connection with said semiconductor chip through said electrically conductive adhesive.

3. (Original) An electronic device, as claimed in Claim 1, wherein said heat spreader is constituted of a heat-absorbing and dissipating material.

4. (Original) An electronic device, as claimed in Claim 2, wherein said heat spreader is selected from the group of materials consisting of copper, silver, aluminum, alumina or alumina silica carbide.

5. (Original) An electronic device, as claimed in Claim 1, wherein said heat spreader comprises a plate-shaped lid or cap member adhesively bonded to said semiconductor chip.

6. (Currently Amended) An electronic device, as claimed in Claim 1, wherein said electrically conductive silicone adhesive ~~comprises a silicone adhesive~~ electrically ~~connecting~~ connects said heat spreader and said semiconductor chip.

7. (Currently Amended) An electronic device, as claimed in Claim 1, wherein said electrically non-conductive silicone adhesive comprises a thermally conductive ~~silicone~~ adhesive for conveying heat from said semiconductor chip to said heat spreader.

8. (Original) An electronic device, as claimed in Claim 1, wherein said electrically conductive adhesive is deposited on the areal surface portion of said semiconductor chip surface to form an about 1 mm diameter bond area with said heat spreader.

9. (Original) An electronic device, as claimed in Claim 8, wherein said electrically non-conductive adhesive is deposited on said semiconductor chip so as to cover the remaining surface area of said chip extending about said electrically conductive adhesive.

10. (Original) An electronic device, as claimed in Claim 8, wherein said heat spreader is spaced from said semiconductor chip to provide a bondline thickness of about 0.025 mm to 0.15 mm for said adhesives.

11. (Currently Amended) A method of forming an electronic device, said method comprising:

providing a semiconductor chip having a first surface in electrical communication with a substrate;

arranging a heat spreader in closely spaced relationship with an opposite surface of said semiconductor chip; and

having adhesive means bond said heat spreader to said semiconductor chip, said adhesive means comprising an electrically conductive silicone adhesive positioned in an essentially single spot formed by said electrically conductive silicone adhesive on a center or an areal surface portion of said semiconductor chip, and an electrically non-conductive silicone adhesive of an extensively larger surface area than said single spot extending about said electrically conductive silicone adhesive for concurrently bonding said heat spreader to said semiconductor chip.

12. (Original) A method, as claimed in Claim 11, wherein said heat spreader comprises an electrically conductive material forming an electrical connection with said semiconductor chip through said electrically conductive adhesive.

13. (Original) A method, as claimed in Claim 11, wherein said heat spreader is constituted of a metallic heat-absorbing and dissipating material.

14. (Original) A method, as claimed in Claim 12, wherein said heat spreader is selected from the group of materials consisting of copper, silver, aluminum, alumina or alumina silica carbide.

15. (Original) A method, as claimed in Claim 11, wherein said heat spreader comprises a plate-shaped lid or cap member adhesively bonded to said semiconductor chip.

16. (Currently Amended) A method, as claimed in Claim 11, wherein said electrically conductive silicone adhesive ~~comprises a silicone adhesive~~ electrically ~~connecting~~ connects said heat spreader and said semiconductor chip.

17. (Currently Amended) A method, as claimed in Claim 11, wherein said electrically non-conductive silicone adhesive comprises a thermally conductive ~~silicone~~ adhesive for conveying heat from said semiconductor chip to said heat spreader.

18. (Original) A method, as claimed in Claim 11, wherein said electrically conductive adhesive is deposited on the areal surface portion of said semiconductor chip surface to form an about 1 mm diameter bond area with said heat spreader.

19. (Original) A method, as claimed in Claim 18, wherein said electrically non-conductive adhesive is deposited on said semiconductor chip so as to cover the remaining surface area of said chip extending about said electrically conductive adhesive.

20. (Original) A method, as claimed in Claim 18, wherein said heat spreader is spaced from said semiconductor chip to provide a bondline thickness of about 0.025 mm to 0.15 mm for said adhesives.